

PIU, BSIA-SICIP

Level#2, Plot # NE (B)-3B, Road # 74, Gulshan-2, Dhaka-1212, Bangladesh

<https://www.bsia-bd.org>

Ref. No.: SICIP/BSIA/Recruitment/2026/128

Date: 18/05/2026

Trainer Recruitment Notice

SICIP-BSIA Program is now looking for suitable candidate to prepare pool for **Lead Trainer** and **Associate Trainer** in various positions in respected courses:

Program Name	:	Skills for Industry Competitiveness and Innovation Program (SICIP)
Agency	:	Bangladesh Semiconductor Industry Association (BSIA)
Scheme Name	:	Advanced Technical Skills, Managerial Capacity and R&D Driven Innovation Capacity Development for Priority and Emerging Industries under SICIP

Information for Applicant:

Courses	Position	Minimum Qualification and Experience
1. IC Design & Layout Engineering	Lead Trainer	<ul style="list-style-type: none">Bachelor's degree /Bachelors of EEE/ECE and or relevant disciplineMinimum 5 years' experience on relevant field.
2. Advanced Physical Design Program: RTL to GDSII		
3. DFT and Verification Engineering Program for ASIC Designers		
4. Applied Semiconductor Systems: Power Devices and Industrial Integration		
5. Smart Systems Engineering: Embedded Design and Semiconductor Application Interfaces		
6. Packaging and Testing		
Associate Trainer	<ul style="list-style-type: none">Bachelor's degree /Bachelors of EEE/ECE and or relevant disciplineMinimum 3 years' experience on relevant field.	
Application Closing Date and Time	The application shall be submitted (Hard Copy) to the office of the Chief Coordinator before 4.00 pm on 8 June, 2026 in sealed envelope clearly marked "Application for the Selection of [Name of Position & Name of the Course/Courses]." Contact address with email and mobile number of the applicant should be written on left side of the A4 Size Envelope. Necessary document in support of educational qualification, experience and skills certificates, one recent passport size photograph, copy of national ID card and other related documents have to be submitted	
Name and Designation of Official Inviting Recruitment:	Rashidul Hassan Chief Coordinator SICIP-BSIA Program	
Address of the Official Inviting Recruitment:	Level#2, Room # 202, Plot #NE (B)-3B, Road # 74, Gulshan-2, Dhaka-1212, Bangladesh	

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Trainers must possess:

- Relevant technical qualifications and industry-recognized certifications
- Practical experience in semiconductor design, testing, fabrication, or related engineering domains
- Familiarity with competency-based learning and ability to facilitate hands-on, Program driven training
- Understanding of workplace safety, green manufacturing practices, and ESD (Electrostatic Discharge) compliance where applicable

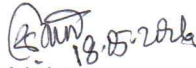
Trainers have the following Skills for each course

SL	Name of the Course	Expected Improvement in Skills
1	IC Design & Layout Engineering	<ul style="list-style-type: none"> • Fundamental Understanding of Analog Circuit Design • Proficiency in Schematic Capture and Simulation Tools • Layout Design Expertise in CMOS Technology • Skill in Matching and Precision Layout Techniques • Parasitic-Aware Design and Post-Layout Verification • Designing and Validating Analog IP Blocks • Understanding of Process Variations and Robus Design • Team-Based Program Development and Documentation • Industry Readiness for Analog Layout and Design Roles
2	Advanced Physical Design Program: RTL to GDSII	<ul style="list-style-type: none"> • Comprehensive Understanding of the ASIC Physical Design Flow • Hands-On Proficiency with Industry-Standard EDA Tools • Expertise in Floor Planning and Power Planning • Mastery of Placement and Clock Tree Synthesis (CTS) • Signal Routing and Congestion Management • Static Timing Analysis and Signoff Checks • Logical Equivalence, DRC, and LVS Signoff Proficiency • Power, IR Drop, and EM Verification Skills • Script-Based Automation of PD Flow • Completion of a Full RTL-to-GDSII Program • Industry Readiness for Physical Design & Backend Engineer Roles
3	DFT and Verification Engineering Program for ASIC Designers	<ul style="list-style-type: none"> • Strong Foundation in Verilog and RTL Design Principles • Mastery of System Verilog and UVM Methodology • Design for Testability (DFT) Fundamentals • Practical Experience with DFT Tools and Flow • Functional Verification and Coverage-Driven Testing • Timing-Aware DFT and Constraints Management • Post-Silicon Readiness and Fault Diagnosis • Debugging and Analysis Using Simulation Tools • Full Program Execution in UVM or DFT Flow • Industry Readiness for DFT and Verification Roles

SL	Name of the Course	Expected Improvement in Skills
4	Applied Semiconductor Systems: Power Devices and Industrial Integration	<ul style="list-style-type: none"> • Component-Level Understanding – Deep knowledge of MOSFETs, IGBTs, diodes, and gate drivers, including their operating principles, characteristics, and application domains. • Switching Behavior & Efficiency Optimization – Ability to analyze and optimize switching performance, reduce losses, and improve system efficiency through proper device selection and control strategies. • Thermal Management Proficiency – Skills in heat dissipation techniques, heat sink sizing, and thermal protection strategies for high-power components. • Power Conversion System Design – Competence in designing and implementing DC-DC converters, inverters, UPS systems, and other industrial power systems. • Control & Automation Integration – Ability to integrate power devices into industrial automation, motor drives, and energy management platforms. • Practical Circuit Skills – Hands-on experience in circuit simulation, PCB design for power electronics, soldering, prototyping, and hardware assembly. • Testing & Troubleshooting – Skills in using measurement instruments (oscilloscopes, multimeters etc.) for testing, diagnosing, and fixing faults in power electronics systems. • Gate Drive Circuit Implementation – Ability to design and configure isolated and non-isolated gate drive circuits for various semiconductor power devices. • Battery & Renewable Energy Applications – Understanding of battery charging systems, battery management systems, and solar inverter integration. • Semiconductor Value Chain Awareness – Knowledge of how discrete power devices are packaged, assembled into modules, and tested, including insight into local and global semiconductor manufacturing practices.
5	Smart Systems Engineering: Embedded Design and Semiconductor Application Interfaces	<ul style="list-style-type: none"> • PCB Design Proficiency – Ability to design schematics, perform PCB layout, and apply best practices for signal integrity, grounding, and EMC compliance. • Embedded Firmware Development – Skills in programming microcontrollers (MCUs) and system-on-chips (SoCs) for real-time control, data processing, and communication. • Sensor Interface & Integration – Competence in interfacing analog and digital sensors using protocols like I²C, SPI, and UART, including calibration and data acquisition. • Hardware-Software Co-Design – Understanding how semiconductor components and firmware interact to deliver functional, optimized embedded systems. • System-Level Debugging & Testing – Ability to troubleshoot hardware and firmware issues using oscilloscopes, logic analyzers, and protocol analyzers. • Prototyping to Productization – Skills to take a concept through schematic capture, PCB fabrication, assembly, firmware deployment, and final testing. • Industrial Application Awareness – Insight into how electronics are deployed in industrial automation, consumer electronics, and IoT applications. • Low-Power Design Practices – Techniques for optimizing firmware and hardware for energy efficiency in battery-powered and IoT devices. • Semiconductor Device Selection – Knowledge of selecting the right MCUs, ICs, and power devices for specific application requirements. • End-to-End Project Management – Ability to manage small-scale electronics projects from concept through to market-ready prototypes.

SL	Name of the Course	Expected Improvement in Skills
6	Packaging and Testing	<ul style="list-style-type: none"> • Clear understanding of how design, fabrication, packaging, and testing inte-grate in the semiconductor value chain. • Understanding of Automatic Test Equipment (ATE) architecture, including PMU, DPS, digital channels, timing systems, and measurement resources. • Ability to develop, debug, and maintain test programs for IC validation and production testing using industry-standard ATE platforms and test methodologies. • Understanding of test coverage concepts, test limits, guard-banding, and correlation between characterization and production testing. • Skills to design and execute DC, AC, and functional tests for digital, analog, and mixed-signal devices. • Skills in analyzing test results, identifying yield loss contributors, and per-forming root-cause analysis at silicon, test, or setup level. • Understanding of IC packaging types (QFN, BGA, CSP, WLCSP, SIP, etc.), package selection criteria, and reliability considerations. • Practical knowledge of die attach, wire bonding, flip-chip bonding, molding, encapsulation, and substrate technologies.

The recruitment entity reserves all the right to accept or reject any or all the Applications without assigning any reason whatsoever.


 Rashidul Hassan
 Chief Coordinator
 SICIP-BSIA Program